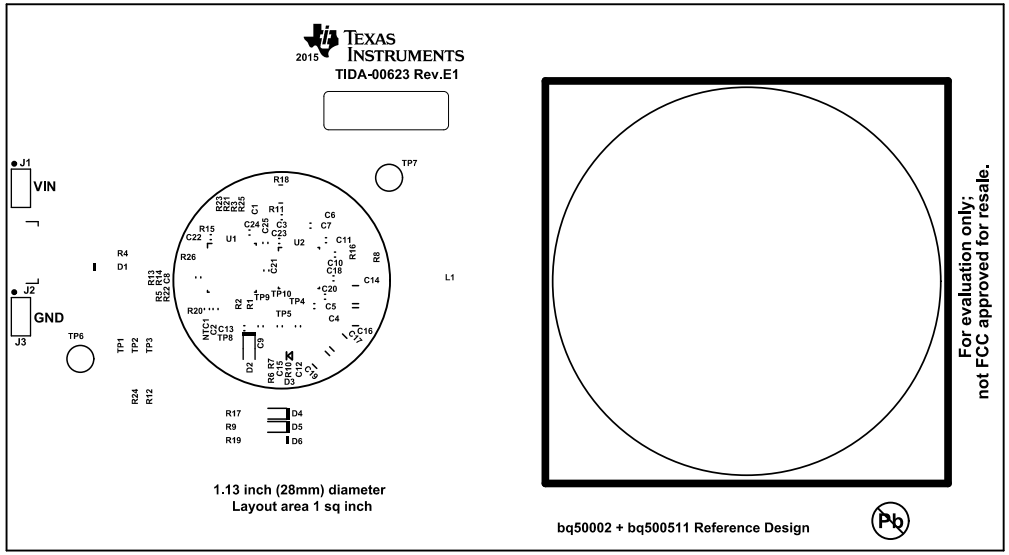
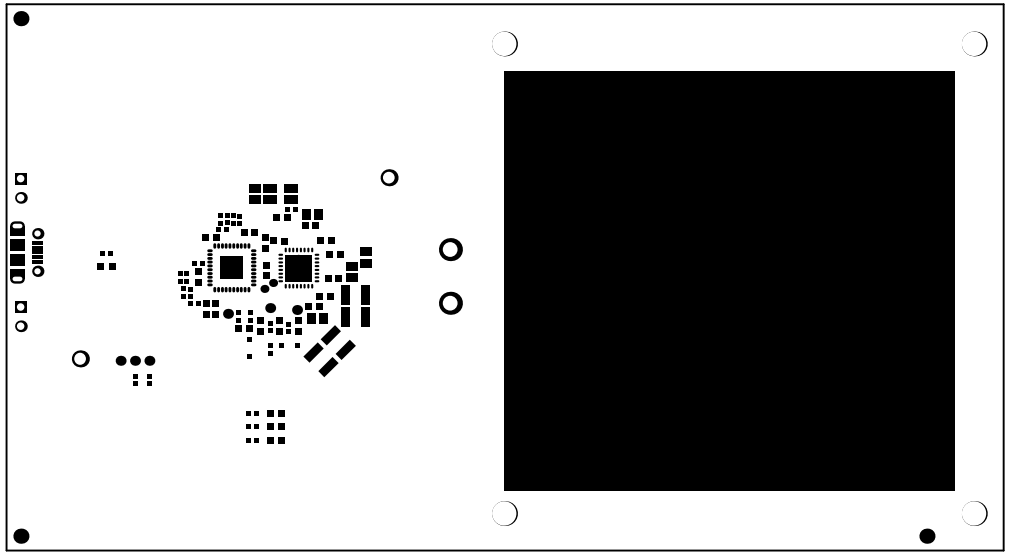
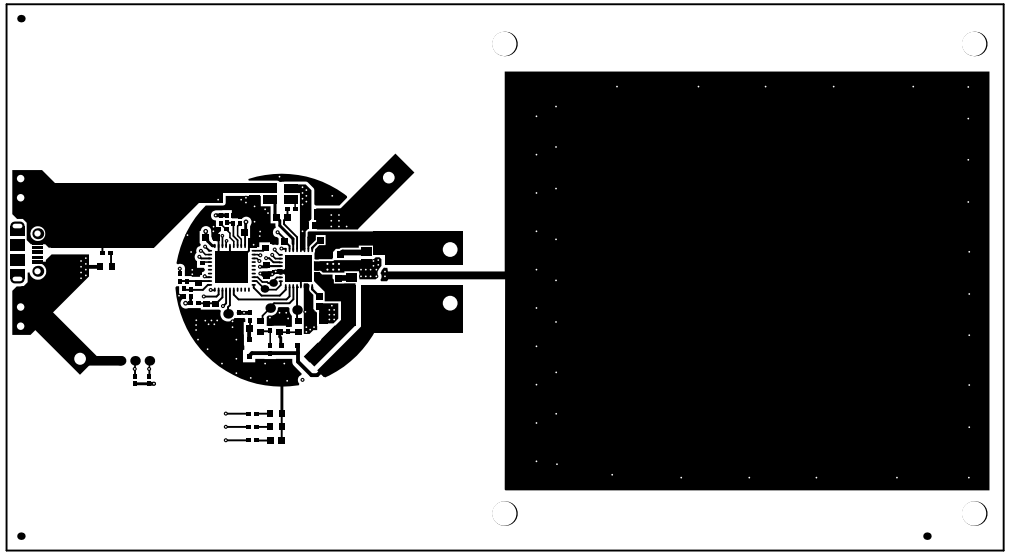


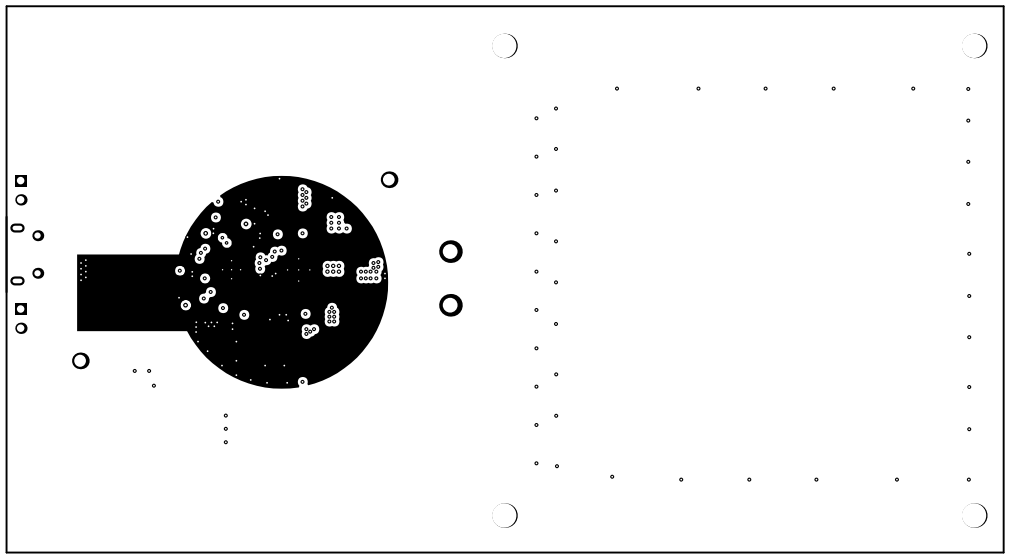

| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 7/8/2015 9:53:13 AM | | TEXAS INSTRUMENTS |



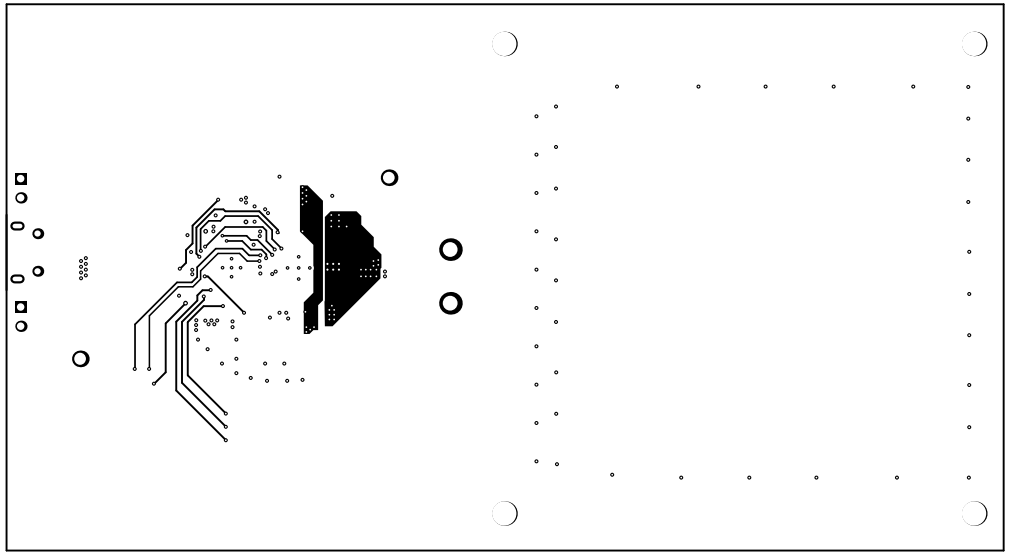
| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 7/8/2015 9:53:14 AM | | TEXAS INSTRUMENTS |



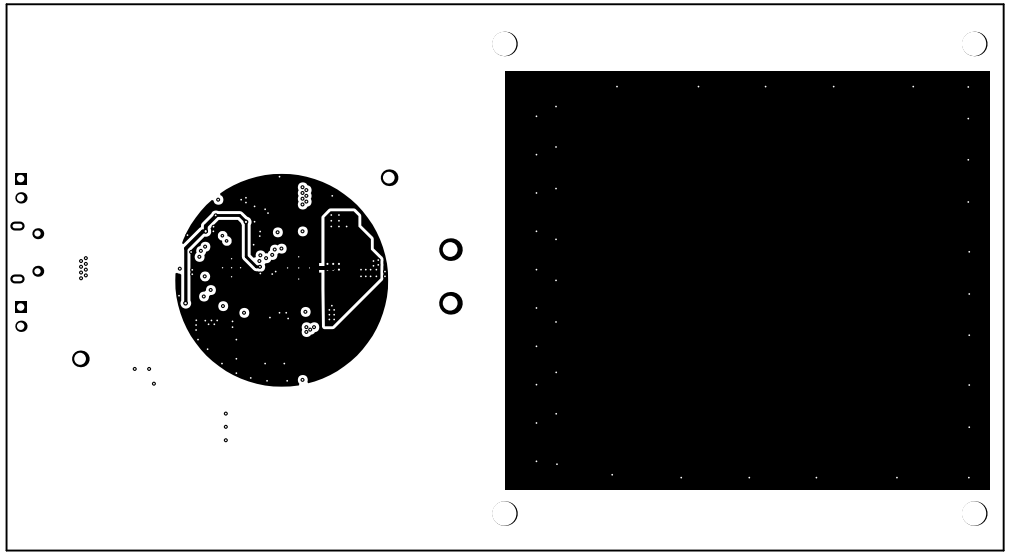
| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
| PLOT NAME = Top Layer | GENERATED : 7/8/2015 9:53:15 AM | | TEXAS INSTRUMENTS |



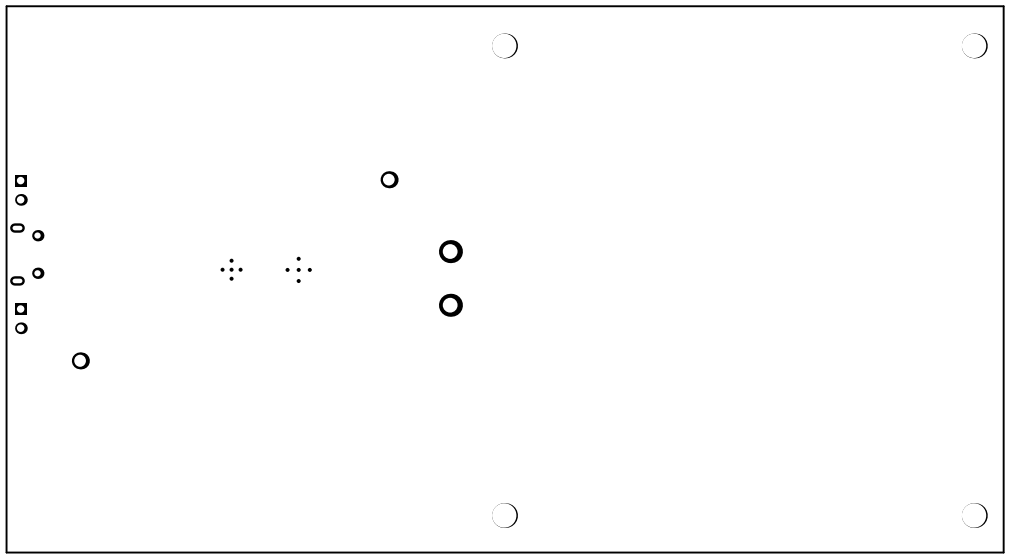
| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = MidLayer1 | | | |
| PLOT NAME = Inner layer 1 | GENERATED : 7/8/2015 9:53:15 AM | | TEXAS INSTRUMENTS |



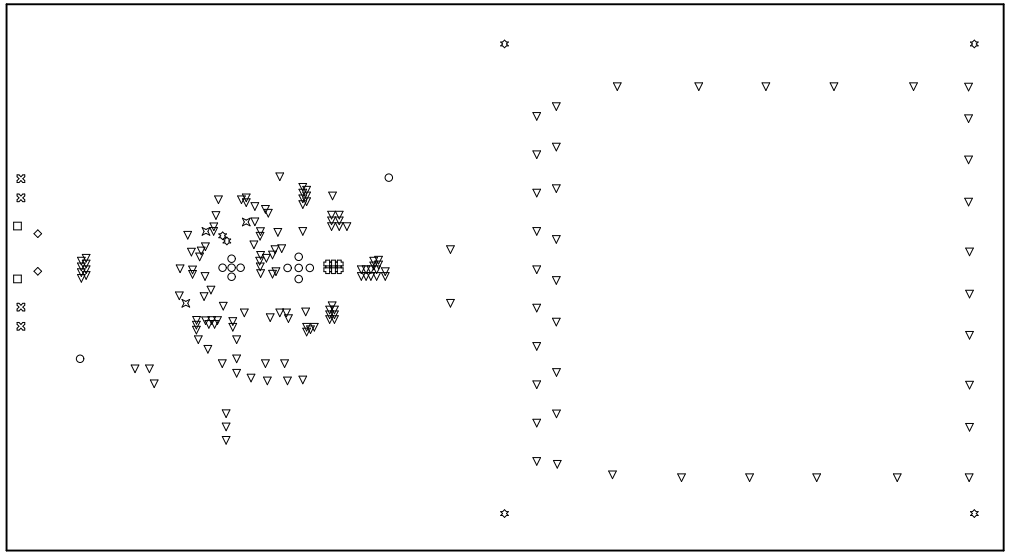
| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = MidLayer2 | | | |
| PLOT NAME = Inner Layer 2 | GENERATED : 7/8/2015 9:53:16 AM | | TEXAS INSTRUMENTS |



| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 7/8/2015 9:53:16 AM | | TEXAS INSTRUMENTS |



| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 7/8/2015 9:53:17 AM | | TEXAS INSTRUMENTS |

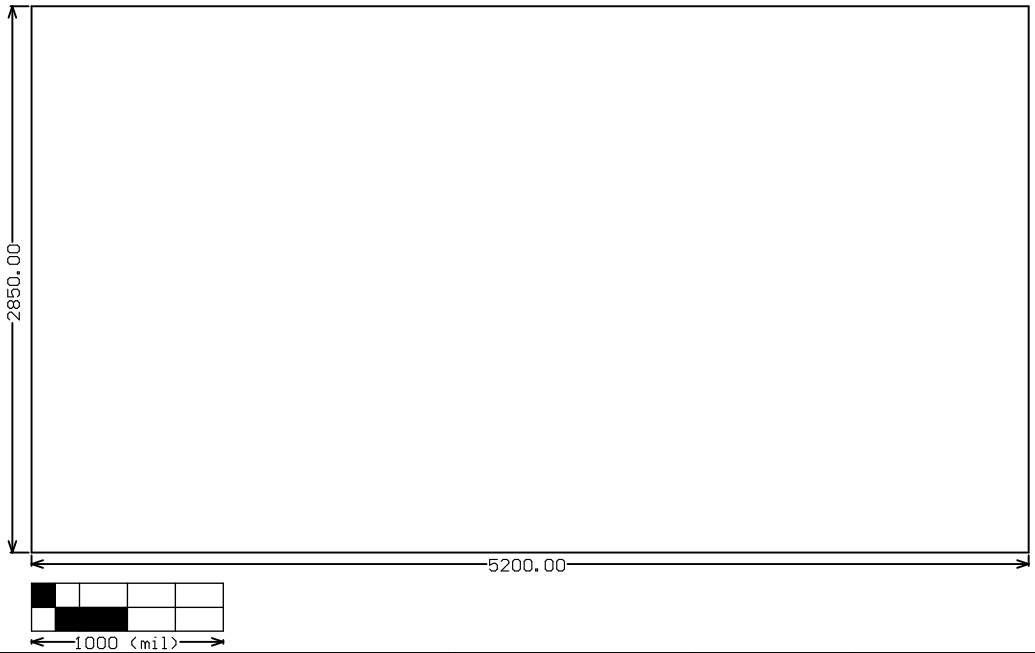


| Symbol | Hit Count | Tool Size | Physical Length | Rout Path Length | Plated | Ho |
|---|---|---|---|---|---|---|
| ○ | 10 | 7.874mil (0.2mm) | | | PTH | Ro |
| ☼ | 2 | 8mil (0.203mm) | | | PTH | Ro |
| ▽ | 161 | 10mil (0.254mm) | | | PTH | Ro |
| ✪ | 6 | 12mil (0.305mm) | | | PTH | Ro |
| ⌑ | 3 | 13mil (0.33mm) | | | PTH | Ro |
| ◇ | 2 | 33.465mil (0.85mm) | | | PTH | Ro |
| ⊠ | 4 | 40mil (1.016mm) | | | PTH | Ro |
| ○ | 2 | 63mil (1.6mm) | | | PTH | Ro |
| ▽ | 2 | 78.74mil (2mm) | | | PTH | Ro |
| ☼ | 4 | 128mil (3.251mm) | | | PTH | Ro |
| □ | 2 | 23.622mil (0.6mm) | 51.181mil (1.3mm) | 27.559mil (0.7mm) | PTH | Sl |
| | 198 Total | | | | | |

**Slot definitions :** **Rout Path Length** = Calculated from tool start centre position to tool end
**Physical Length** = Rout Path Length + Tool Size = Slot length as defined

Drill Table

| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 7/8/2015 9:53:17 AM | | TEXAS INSTRUMENTS |




| | | | | |
|---|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00623 | REV: E1 | SVN REV: Not In VersionControl | |
| LAYER NAME = M2 Board Dimensions | | | | |
| PLOT NAME = Board Dimensions | GENERATED : 7/8/2015 9:53:18 AM | | | TEXAS INSTRUMENTS |

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